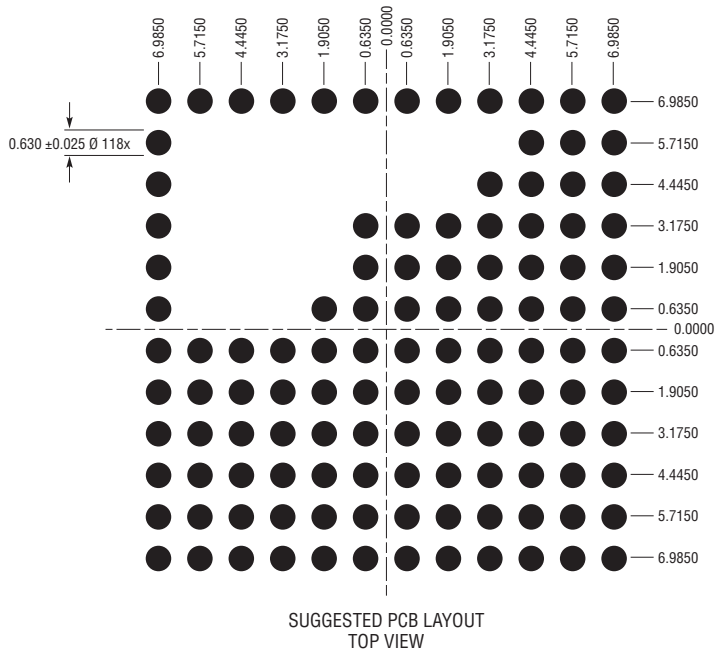
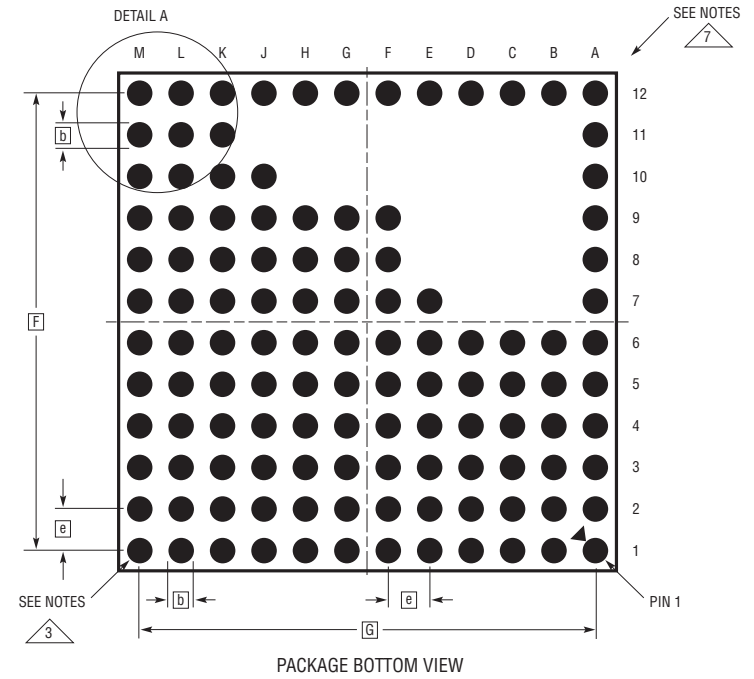
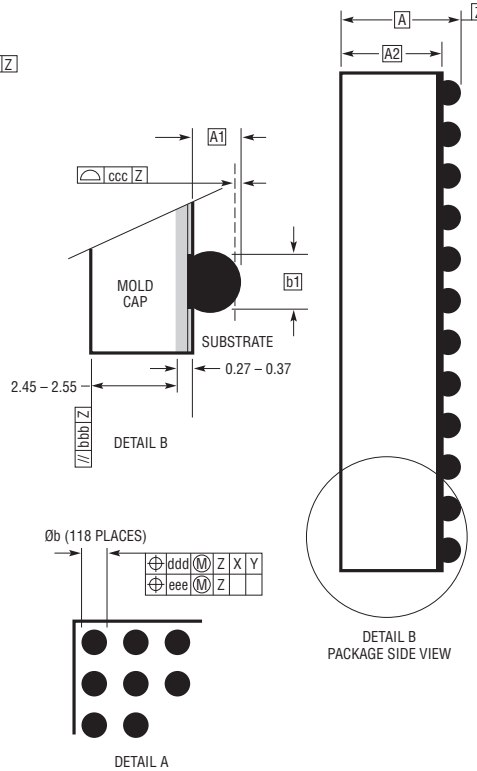
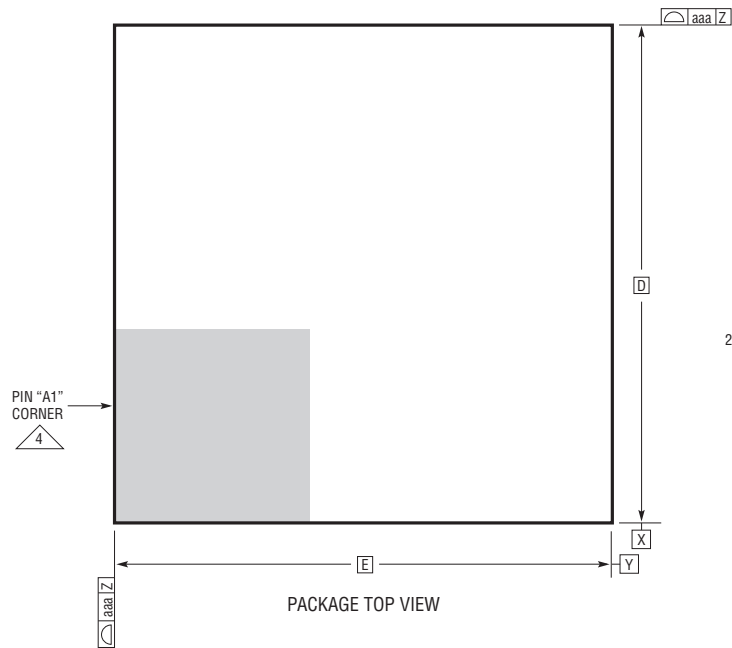


BGA Package
118-Lead (15mm × 15mm × 3.42mm)
 (Reference LTC DWG # 05-08-1903 Rev B)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.22	3.42	3.62	
A1	0.50	0.60	0.70	
A2	2.72	2.82	2.92	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D	15.0			
E	15.0			
e	1.27			
F	13.97			
G	13.97			
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 118

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu

7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

